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AT&T TECHNICAL JOURNAL

1992 INDEX AND CONTENTS

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AT&T TECHNICAL JOURNAL (ISSN 8756-2324)
is published six times a year by AT&T. Current price of individual subscriptions:
U.S.—1 year $50; 2 years $90; 3 years $120
Foreign—1 year $64; 2 years $118; 3 years $162.

Payment for subscriptions must be made by check in U.S. funds, drawn on a U.S. bank, and made payable to the *AT&T Technical Journal*. Send subscription requests with payment to Circulation Group, Room 3C–417, AT&T Bell Laboratories, 600 Mountain Ave., P.O. Box 636, Murray Hill, NJ 07974-0636.

Current or recent issues may be obtained by writing to the Circulation Group or calling 908 582–4019 or 4823. Photocopy or microform reprints from the *Journal* are available by writing to University Microfilms International, 300 N. Zeeb Road, Ann Arbor, MI 48106, or calling 800 521–0600. From outside the U.S., call 313 761–4700

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IC *See* Integrated circuits
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ICOLP *See* Industry Cooperative for Ozone Layer Protection
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